

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



### Contact us

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# HI1206T500R-10

### **UNCONTROLLED DOCUMENT**

### PHYSICAL DIMENSIONS:

**IMPEDANCE** 

A 3.20 [.126] ± 0.20 [.008] B 1.60 [.063] ± 0.20 [.008] C 1.10 [.043] + 0.20 [.008]

D 0.51 [.020] ± 0.25 [.010]

# Z vs. FREQUENCY IMPEDANCE UNDER DC BIAS - 0amp · 1amp 2amp - 3amp 4amp 5amp

100

ELECTRICAL CHARACTERISTICS:											
Z @ 100M ( <u>Ω</u> )	1Hz	DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current								
Nominal	50										
Minimum	38										
Maximum	63	0.010	6000 mA								

NOTES: UNLESS OTHERWISE SPECIFIED

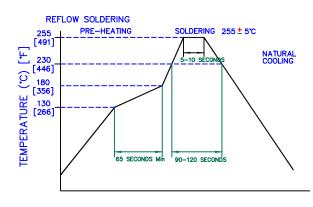
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. TERMINATION FINISH IS 100% TIN.
- 4. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

#### LAND PATTERNS FOR REFLOW SOLDERING

## 1.13 [.044] 2.06 [.081] 4.65 [.183]

(For wave soldering, add 0.762 [.030] to this dimension)

#### RECOMMENDED SOLDERING CONDITIONS



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FREQUENCY (MHz)



	DIMENSIONS ARE IN mm [INCHE	ES].	This print is the property of Lair						
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				with the understanding that no	maj	•	2	1	
				copies shall be made without the		u	II ŧ		
				written consent of Laird Tech. All rights to design or invention are		_			
				reserved.					
D	D ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE		OII	PROJECT/PART NUMBER:	┰	EV	PART TO	PE:	DRAWN BY:
U				HI1206T500R-10	-	D	CO-FIRE		JRK
С	UPDATE COMPANY LOGO & ROHS SYM.	01/17/08	JRK	1111200100011 10	-	_	00-	FIRE	J 57.11.
В	ADD ROHS SYMBOL AND NOTE 3	10/01/04	JRK	DATE: 03/02/04 S	CAL	E: N	TS	SHEET:	
Α	ORIGINAL DRAFT	03/02/04	JRK		TOOL			2	of 2
REV	DESCRIPTION	DATE	INT			•	-	_	01 2

AGILENT E4991A RF Impedance/Material Analyzer HP 16092A Test Fixture. TEST REF. 3185